



PSMN041-80YL

N-channel 80 V 41 mΩ logic level MOSFET in LFPAK56

1 May 2013

Product data sheet

1. General description

Logic level gate drive N-channel enhancement mode Field-Effect Transistor (FET) in LFPAK56 package. This product has been designed and qualified for use in a wide range of industrial, communications and domestic equipment.

2. Features and benefits

- High efficiency due to low switching and conduction losses
- Suitable for logic level gate drive
- LFPAK56 package is footprint compatible with other Power-SO8 types
- Qualified to 175 °C

3. Applications

- DC-to-DC converters
- Load switch
- TV power supplies

4. Quick reference data

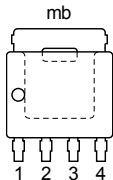
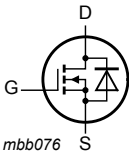
Table 1. Quick reference data

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--------------------------------|----------------------------------|---|-----|------|-----|------|
| V_{DS} | drain-source voltage | $T_j \geq 25\text{ °C}; T_j \leq 175\text{ °C}$ | - | - | 80 | V |
| I_D | drain current | $T_{mb} = 25\text{ °C}; V_{GS} = 10\text{ V}; \text{Fig. 1}$ | - | - | 25 | A |
| P_{tot} | total power dissipation | $T_{mb} = 25\text{ °C}; \text{Fig. 2}$ | - | - | 64 | W |
| Static characteristics | | | | | | |
| $R_{DS(on)}$ | drain-source on-state resistance | $V_{GS} = 10\text{ V}; I_D = 5\text{ A}; T_j = 25\text{ °C}; \text{Fig. 12}$ | - | 32.8 | 41 | mΩ |
| | | $V_{GS} = 10\text{ V}; I_D = 5\text{ A}; T_j = 175\text{ °C}; \text{Fig. 13}; \text{Fig. 12}$ | - | - | 103 | mΩ |
| Dynamic characteristics | | | | | | |
| Q_{GD} | gate-drain charge | $V_{GS} = 10\text{ V}; I_D = 5\text{ A}; V_{DS} = 64\text{ V};$ | - | 4.3 | - | nC |
| $Q_{G(tot)}$ | total gate charge | $T_j = 25\text{ °C}; \text{Fig. 14}; \text{Fig. 15}$ | - | 21.9 | - | nC |

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-----------------------------|--|--|-----|-----|------|------|
| Avalanche ruggedness | | | | | | |
| $E_{DS(AL)S}$ | non-repetitive drain-source avalanche energy | $V_{GS} = 10\text{ V}$; $T_{j(\text{init})} = 25\text{ °C}$; $I_D = 25\text{ A}$; $V_{\text{sup}} \leq 80\text{ V}$; $R_{GS} = 50\text{ }\Omega$; unclamped; Fig. 3 | - | - | 23.9 | mJ |

5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|-----------------------------------|--|--|
| 1 | S | source |  <p>LFAK56; Power-SO8 (SOT669)</p> |  <p><i>mbb076</i></p> |
| 2 | S | source | | |
| 3 | S | source | | |
| 4 | G | gate | | |
| mb | D | mounting base; connected to drain | | |

6. Ordering information

Table 3. Ordering information

| Type number | Package | | |
|--------------|-------------------|---|---------|
| | Name | Description | Version |
| PSMN041-80YL | LFAK56; Power-SO8 | Plastic single-ended surface-mounted package (LFAK56; Power-SO8); 4 leads | SOT669 |

7. Marking

Table 4. Marking codes

| Type number | Marking code |
|--------------|--------------|
| PSMN041-80YL | 04180 |

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------|----------------------|---|-----|-----|------|
| V_{DS} | drain-source voltage | $T_j \geq 25\text{ °C}$; $T_j \leq 175\text{ °C}$ | - | 80 | V |
| V_{DGR} | drain-gate voltage | $T_j \geq 25\text{ °C}$; $T_j \leq 175\text{ °C}$; $R_{GS} = 20\text{ k}\Omega$ | - | 80 | V |
| V_{GS} | gate-source voltage | | -20 | 20 | V |
| I_D | drain current | $V_{GS} = 10\text{ V}$; $T_{\text{mb}} = 100\text{ °C}$; Fig. 1 | - | 18 | A |

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------------------------|--|---|-----|------|------|
| | | $V_{GS} = 10\text{ V}$; $T_{mb} = 25\text{ °C}$; Fig. 1 | - | 25 | A |
| I_{DM} | peak drain current | pulsed; $t_p \leq 10\text{ }\mu\text{s}$; $T_{mb} = 25\text{ °C}$; Fig. 4 | - | 100 | A |
| P_{tot} | total power dissipation | $T_{mb} = 25\text{ °C}$; Fig. 2 | - | 64 | W |
| T_{stg} | storage temperature | | -55 | 175 | °C |
| T_j | junction temperature | | -55 | 175 | °C |
| $T_{sld(M)}$ | peak soldering temperature | | - | 260 | °C |
| Source-drain diode | | | | | |
| I_S | source current | $T_{mb} = 25\text{ °C}$ | - | 54 | A |
| I_{SM} | peak source current | pulsed; $t_p \leq 10\text{ }\mu\text{s}$; $T_{mb} = 25\text{ °C}$ | - | 100 | A |
| Avalanche ruggedness | | | | | |
| $E_{DS(AL)S}$ | non-repetitive drain-source avalanche energy | $V_{GS} = 10\text{ V}$; $T_{j(\text{init})} = 25\text{ °C}$; $I_D = 25\text{ A}$; $V_{sup} \leq 80\text{ V}$; $R_{GS} = 50\text{ }\Omega$; unclamped; Fig. 3 | - | 23.9 | mJ |

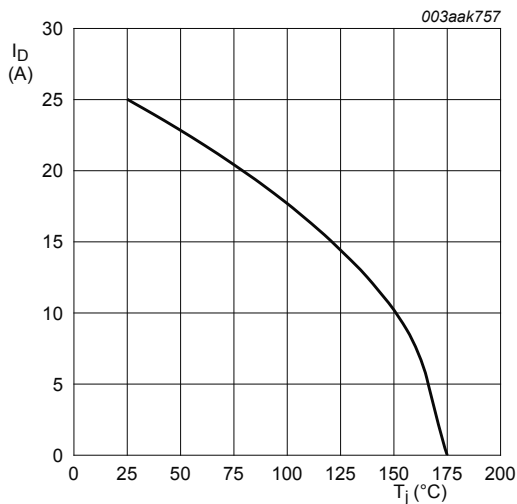


Fig. 1. Continuous drain current as a function of mounting base temperature

$$V_{GS} \geq 10V$$

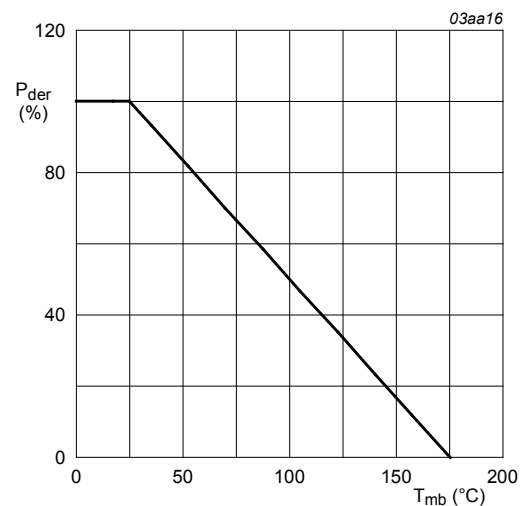


Fig. 2. Normalized total power dissipation as a function of mounting base temperature

$$P_{der} = \frac{P_{tot}}{P_{tot(25^\circ\text{C})}} \times 100\%$$

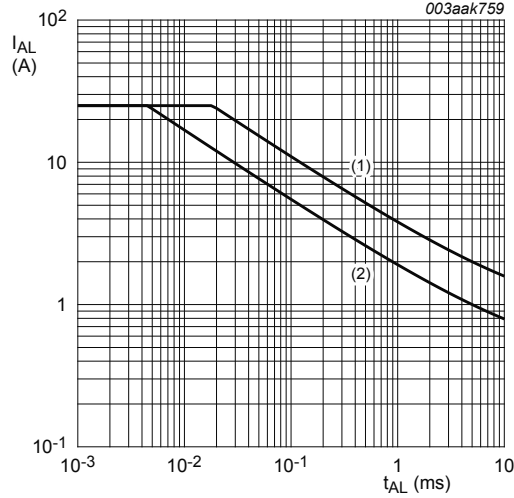


Fig. 3. Avalanche rating; avalanche current as a function of avalanche time

(1) $T_{j(jnt)} = 25^{\circ}C$; (2) $T_{j(jnt)} = 100^{\circ}C$

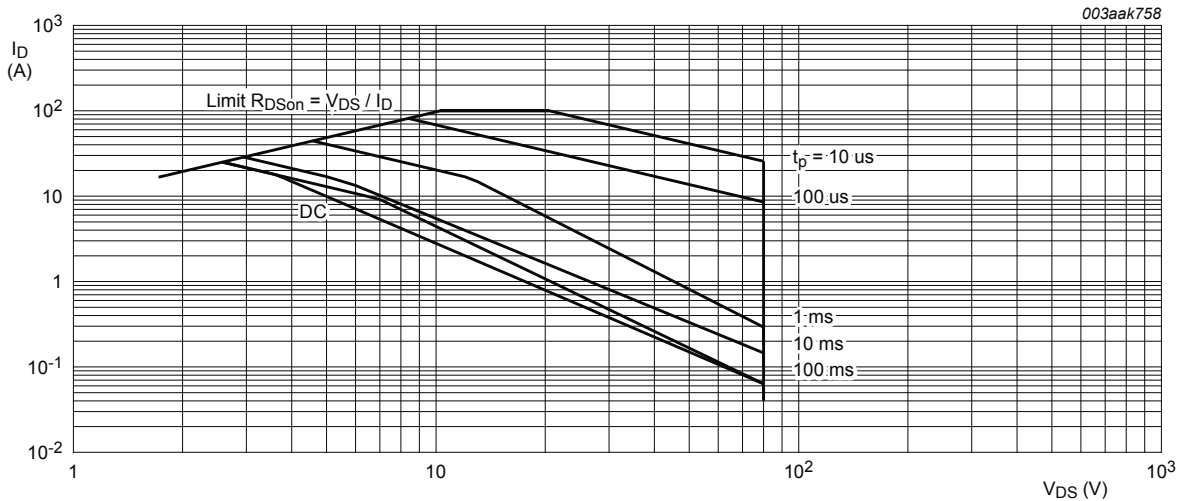


Fig. 4. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

$T_{mb} = 25^{\circ}C$; I_{DM} is a single pulse

9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|----------------|---|------------|-----|------|------|------|
| $R_{th(j-mb)}$ | thermal resistance from junction to mounting base | Fig. 5 | - | 2.13 | 2.33 | K/W |

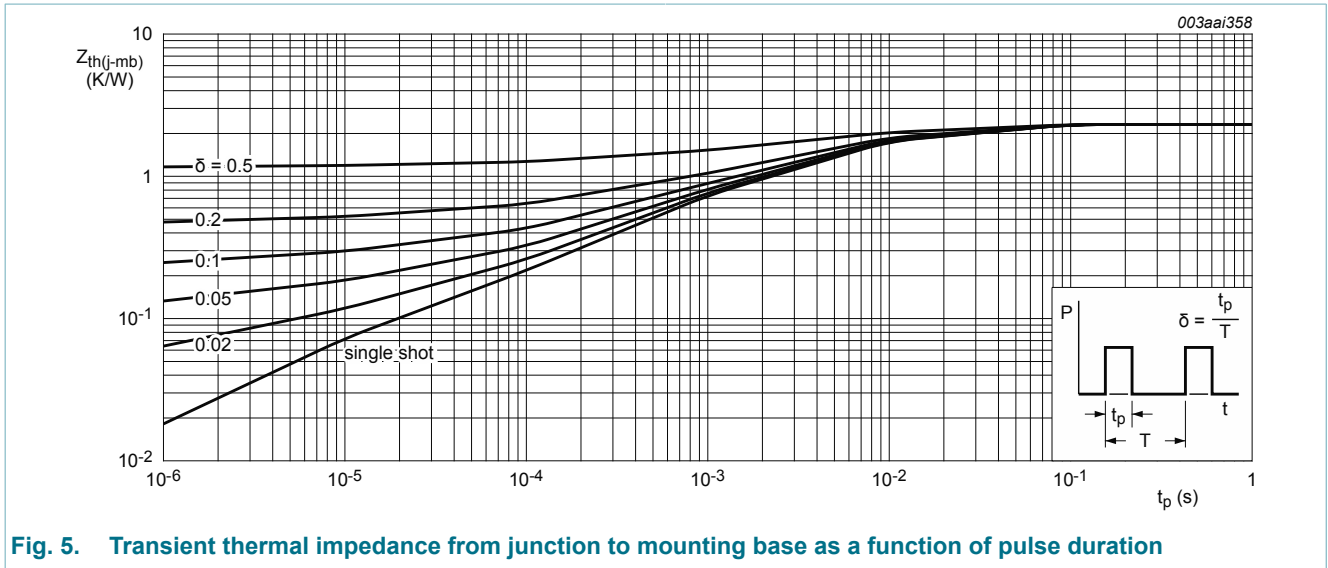


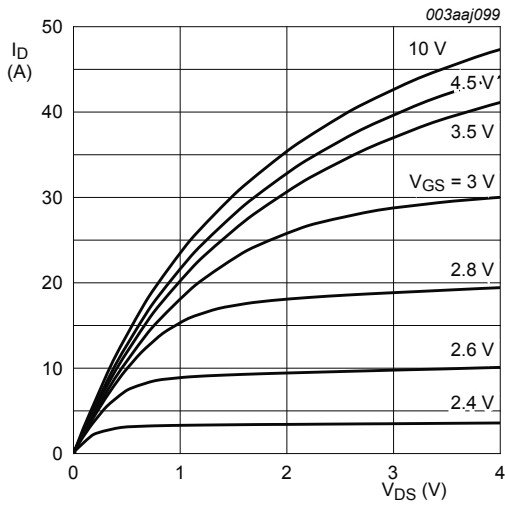
Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

Table 7. Characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------------------------|----------------------------------|---|-----|------|------|---------|
| Static characteristics | | | | | | |
| $V_{(BR)DSS}$ | drain-source breakdown voltage | $I_D = 250 \mu A; V_{GS} = 0 V; T_j = -55 \text{ }^\circ C$ | 72 | - | - | V |
| | | $I_D = 250 \mu A; V_{GS} = 0 V; T_j = 25 \text{ }^\circ C$ | 80 | - | - | V |
| $V_{GS(th)}$ | gate-source threshold voltage | $I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 175 \text{ }^\circ C;$ Fig. 10 | 0.5 | - | - | V |
| | | $I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = -55 \text{ }^\circ C;$ Fig. 10 | - | - | 2.45 | V |
| | | $I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 25 \text{ }^\circ C;$ Fig. 10; Fig. 11 | 1.4 | 1.7 | 2.1 | V |
| I_{DSS} | drain leakage current | $V_{DS} = 80 V; V_{GS} = 0 V; T_j = 25 \text{ }^\circ C$ | - | 0.02 | 1 | μA |
| | | $V_{DS} = 80 V; V_{GS} = 0 V; T_j = 175 \text{ }^\circ C$ | - | - | 500 | μA |
| I_{GSS} | gate leakage current | $V_{GS} = -16 V; V_{DS} = 0 V; T_j = 25 \text{ }^\circ C$ | - | - | 100 | nA |
| | | $V_{GS} = 16 V; V_{DS} = 0 V; T_j = 25 \text{ }^\circ C$ | - | - | 100 | nA |
| R_{DSon} | drain-source on-state resistance | $V_{GS} = 10 V; I_D = 5 A; T_j = 25 \text{ }^\circ C;$ Fig. 12 | - | 32.8 | 41 | mΩ |
| | | $V_{GS} = 5 V; I_D = 5 A; T_j = 175 \text{ }^\circ C;$ Fig. 13; Fig. 12 | - | - | 113 | mΩ |
| | | $V_{GS} = 10 V; I_D = 5 A; T_j = 175 \text{ }^\circ C;$ Fig. 13; Fig. 12 | - | - | 103 | mΩ |
| | | $V_{GS} = 5 V; I_D = 5 A; T_j = 25 \text{ }^\circ C;$ Fig. 12 | - | 35.7 | 45 | mΩ |
| R_G | gate resistance | $f = 1 \text{ MHz}$ | - | 2.02 | - | Ω |

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--------------------------------|-----------------------------------|--|-----|------|-----|------|
| Dynamic characteristics | | | | | | |
| Q _{G(tot)} | total gate charge | I _D = 5 A; V _{DS} = 64 V; V _{GS} = 10 V; T _j = 25 °C; Fig. 14 ; Fig. 15 | - | 21.9 | - | nC |
| | | I _D = 5 A; V _{DS} = 64 V; V _{GS} = 5 V; T _j = 25 °C; Fig. 14 ; Fig. 15 | - | 11.9 | - | nC |
| Q _{GS} | gate-source charge | I _D = 5 A; V _{DS} = 64 V; V _{GS} = 10 V; T _j = 25 °C; Fig. 14 ; Fig. 15 | - | 2.5 | - | nC |
| Q _{GS(th)} | pre-threshold gate-source charge | | - | 1.7 | - | nC |
| Q _{GS(th-pl)} | post-threshold gate-source charge | | - | 0.8 | - | nC |
| Q _{GD} | gate-drain charge | | - | 4.3 | - | nC |
| V _{GS(pl)} | gate-source plateau voltage | I _D = 5 A; V _{DS} = 64 V; T _j = 25 °C; Fig. 14 ; Fig. 15 | - | 2.4 | - | V |
| C _{iss} | input capacitance | V _{DS} = 25 V; V _{GS} = 0 V; f = 1 MHz; T _j = 25 °C; Fig. 16 | - | 1180 | - | pF |
| C _{oss} | output capacitance | | - | 99 | - | pF |
| C _{rss} | reverse transfer capacitance | | - | 54 | - | pF |
| t _{d(on)} | turn-on delay time | V _{DS} = 60 V; R _L = 10 Ω; V _{GS} = 5 V; R _{G(ext)} = 5 Ω; T _j = 25 °C | - | 8.6 | - | ns |
| t _r | rise time | | - | 11.2 | - | ns |
| t _{d(off)} | turn-off delay time | | - | 16.1 | - | ns |
| t _f | fall time | | - | 10.5 | - | ns |
| Source-drain diode | | | | | | |
| V _{SD} | source-drain voltage | I _S = 5 A; V _{GS} = 0 V; T _j = 25 °C; Fig. 17 | - | 0.8 | 1.2 | V |
| t _{rr} | reverse recovery time | I _S = 5 A; di/dt = 100 A/μs; V _{GS} = 0 V; V _{DS} = 25 V; T _j = 25 °C | - | 21.3 | - | ns |
| Q _r | recovered charge | | - | 22 | - | nC |



$T_j = 25^\circ\text{C}; t_p = 300 \mu\text{s}$

Fig. 6. Output characteristics; drain current as a function of drain-source voltage; typical values

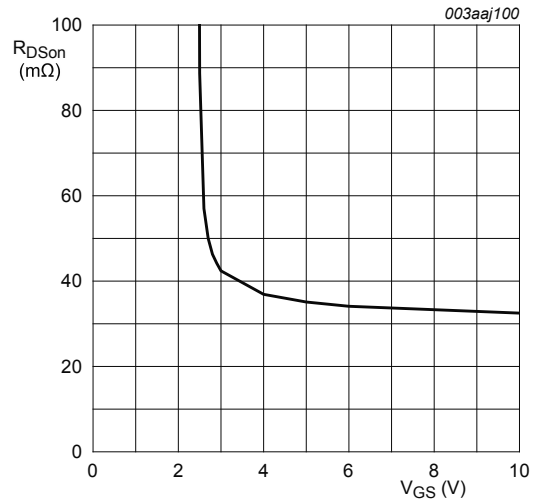


Fig. 7. Drain-source on-state resistance as a function of gate-source voltage; typical values

$T_j = 25^\circ\text{C}; I_D = 5\text{A}$

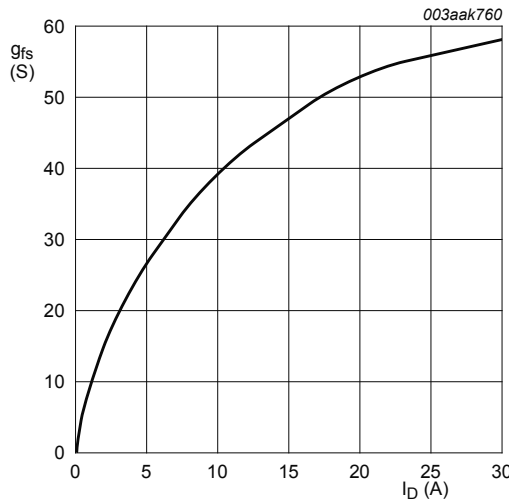


Fig. 8. Forward transconductance as a function of drain current; typical values

$T_j = 25^\circ\text{C}; V_{DS} = 10\text{V}$

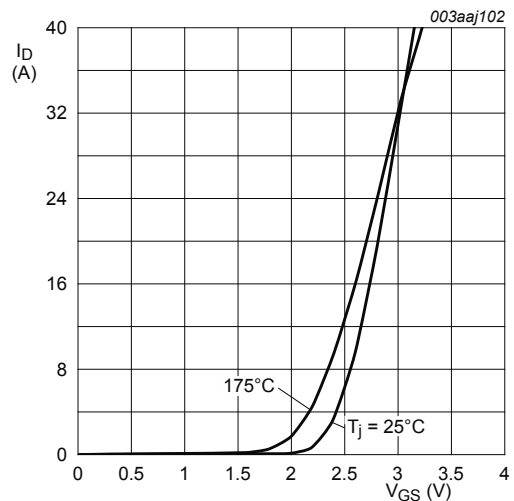


Fig. 9. Transfer characteristics; drain current as a function of gate-source voltage; typical values

$V_{DS} = 10\text{V}$

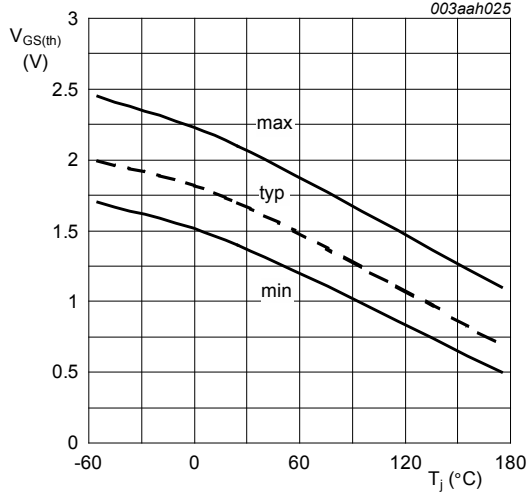


Fig. 10. Gate-source threshold voltage as a function of junction temperature

$$I_D = 1 \text{ mA}; V_{DS} = V_{GS}$$

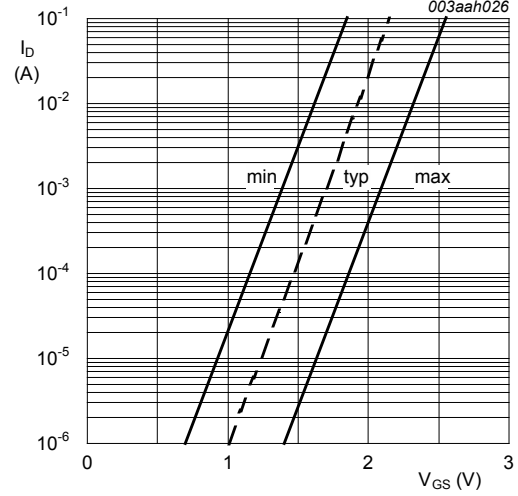
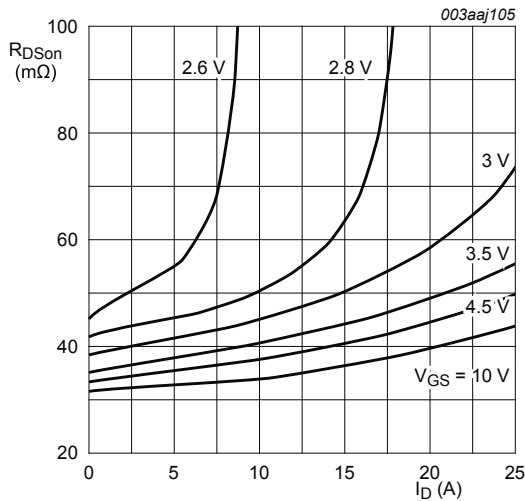


Fig. 11. Sub-threshold drain current as a function of gate-source voltage

$$T_j = 25^\circ\text{C}; V_{DS} = 5\text{V}$$



$$T_j = 25^\circ\text{C}; t_p = 300 \mu\text{s}$$

Fig. 12. Drain-source on-state resistance as a function of drain current; typical values

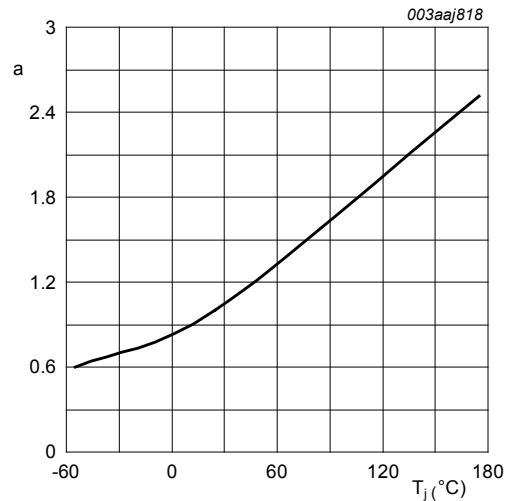


Fig. 13. Normalized drain-source on-state resistance factor as a function of junction temperature

$$a = \frac{R_{DS(on)}}{R_{DS(on)}(25^\circ\text{C})}$$

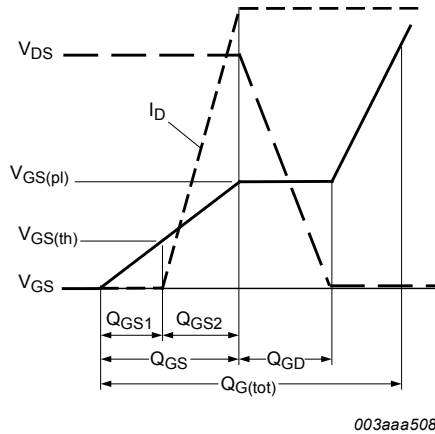


Fig. 14. Gate charge waveform definitions

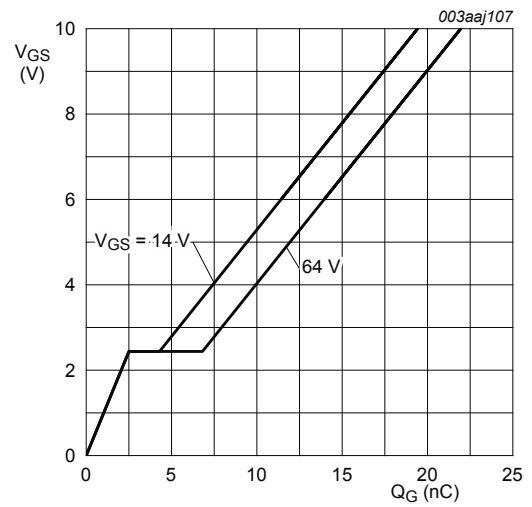


Fig. 15. Gate-source voltage as a function of gate charge; typical values

$T_j = 25^\circ\text{C}; I_D = 5\text{A}$

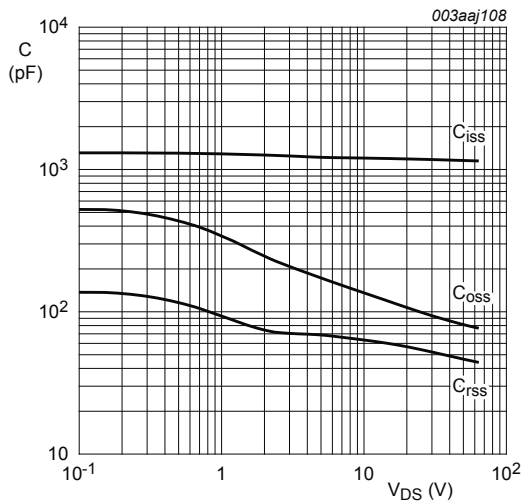


Fig. 16. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

$V_{GS} = 0\text{V}; f = 1\text{MHz}$

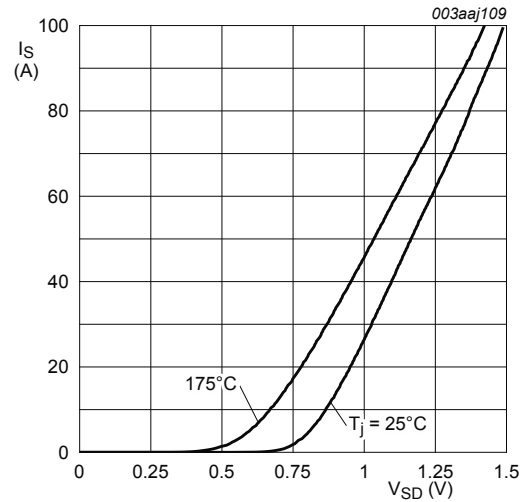
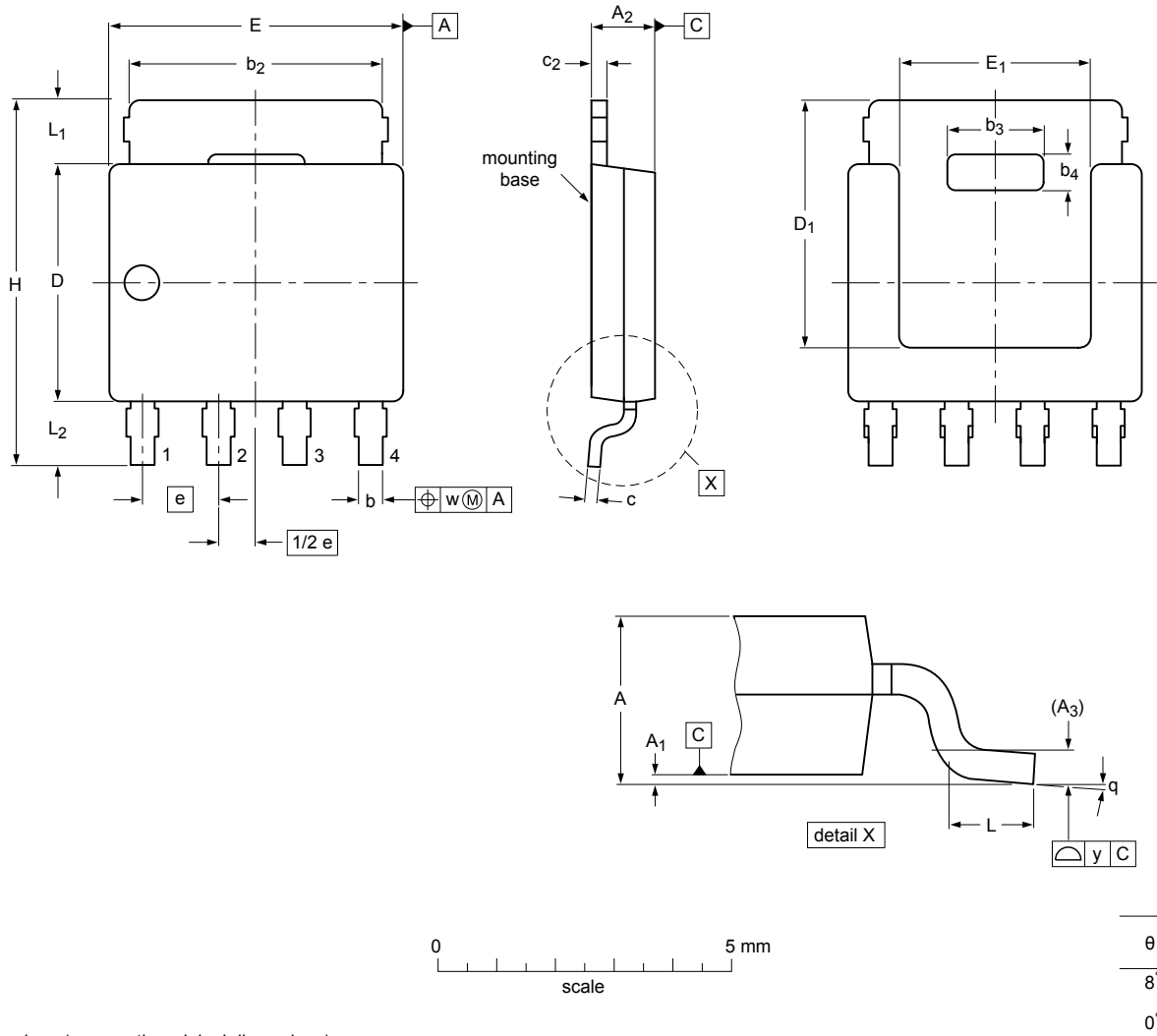


Fig. 17. Source-drain (diode forward) current as a function of source-drain (diode forward) voltage; typical values

$V_{GS} = 0\text{V}$

11. Package outline

Plastic single-ended surface-mounted package (LPAK56; Power-SO8); 4 leads SOT669



Dimensions (mm are the original dimensions)

| Unit ⁽¹⁾ | A | A ₁ | A ₂ | A ₃ | b | b ₂ | b ₃ | b ₄ | c | c ₂ | D ⁽¹⁾ | D ₁ ⁽¹⁾ | E ⁽¹⁾ | E ₁ ⁽¹⁾ | e | H | L | L ₁ | L ₂ | w | y |
|---------------------|------|----------------|----------------|----------------|------|----------------|----------------|----------------|------|----------------|------------------|-------------------------------|------------------|-------------------------------|------|-----|------|----------------|----------------|------|-----|
| max | 1.20 | 0.15 | 1.10 | | 0.50 | 4.41 | 2.2 | 0.9 | 0.25 | 0.30 | 4.10 | 4.20 | 5.0 | 3.3 | | 6.2 | 0.85 | 1.3 | 1.3 | | |
| nom | | | | 0.25 | | | | | | | | | | | 1.27 | | | | | 0.25 | 0.1 |
| min | 1.01 | 0.00 | 0.95 | | 0.35 | 3.62 | 2.0 | 0.7 | 0.19 | 0.24 | 3.80 | | 4.8 | 3.1 | | 5.8 | 0.40 | 0.8 | 0.8 | | |

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

sot669_po

| Outline version | References | | | | European projection | Issue date |
|-----------------|------------|--------|-------|--|---------------------|------------------------|
| | IEC | JEDEC | JEITA | | | |
| SOT669 | | MO-235 | | | | -11-03-25- 13-02-27 |

Fig. 18. Package outline LPAK56; Power-SO8 (SOT669)

12. Legal information

12.1 Data sheet status

| Document status [1][2] | Product status [3] | Definition |
|--------------------------------|--------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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13. Contents

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Date of release: 01 May 2013